

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2883363

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>SEQUENCE:</b>	8

**CONVEYING PARTY DATA**

Name	Execution Date
SAMSUNG FINE CHEMICALS CO., LTD.	04/29/2014
SAMSUNG ELECTRONICS CO., LTD.	04/18/2014

**RECEIVING PARTY DATA**

<b>Name:</b>	SAMSUNG ELECTRO-MECHANICS CO., LTD.
<b>Street Address:</b>	314, MAETAN-3DONG, YEONGTONG-GU
<b>City:</b>	SUWON-SI, GYEONGGI-DO
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>Postal Code:</b>	443-803

**PROPERTY NUMBERS Total: 8**

Property Type	Number
Application Number:	12263598
Application Number:	12621043
Application Number:	12489881
Application Number:	12123748
Application Number:	12328458
Application Number:	12173237
Application Number:	12332931
Application Number:	12633127

**CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: PHO0188US ET AL.(8)

PATENT

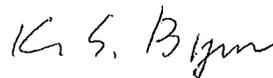
<b>NAME OF SUBMITTER:</b>	LEAH M. REIMER
<b>SIGNATURE:</b>	/Leah M. Reimer/
<b>DATE SIGNED:</b>	06/04/2014
<b>Total Attachments: 4</b> source=7641711#page1.tif source=7641711#page2.tif source=7641711#page3.tif source=7641711#page4.tif	

CONFIRMATORY PATENT ASSIGNMENT

For valuable consideration, the receipt of which is hereby acknowledged, *SAMSUNG FINE CHEMICALS CO., LTD.*, a corporation of the *Republic of Korea*, having its principal place of business at 190 Yeochon-dong, Nam-gu, Ulsan 680-090, Republic of Korea, hereby assigns to **Samsung Electro-Mechanics Co., Ltd.**, a corporation organized and existing under the laws of the Country of Republic of Korea, having a place of business at **314, Maetan-3dong, Yeongtong-gu, Suwon-si, Gyeonggi-do 443-803, Republic of Korea**, all of the right, title and interest of *SAMSUNG FINE CHEMICALS CO., LTD.*, in and to the patents and patent applications listed on the attached Schedule of U.S. Patents and Patent Applications.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

*SAMSUNG FINE CHEMICALS CO., LTD.*,  
*Republic of Korea Corporation*



By:           Kil Seuk BYUN          

Title:     IP Team Leader

Date:           2014. 04. 29

**SCHEDULE OF U.S. PATENTS**

	<b>U.S. APPLICATION PATENT NUMBER</b>	<b>FILING DATE</b>	<b>TITLE</b>
1.	12/263,598	11/03/2008	COMPOSITION FOR PRODUCING BOARD AND PRINTED CIRCUIT BOARD USING THE SAME
2.	12/621,043	11/18/2009	THERMOSETTING COMPOSITION AND PRINTED CIRCUIT BOARD USING THE SAME
3.	12/489,881	06/23/2009	THERMOSETTING OLIGOMER OR POLYMER, THERMOSETTING RESIN COMPOSITION INCLUDING THE OLIGOMER OR POLYMER, AND PRINTED CIRCUIT BOARD USING THE COMPOSITION
4.	12/123,748	05/20/2008	LIQUID CRYSTAL POLYESTER RESIN COMPOSITION AND PRINTED CIRCUIT BOARD USING THE SAME
5.	12/328,458	12/04/2008	COMPOSITION FOR PRODUCING PRINTED CIRCUIT BOARD AND PRINTED CIRCUIT BOARD USING THE SAME
6.	12/173,237	07/15/2008	LIQUID CRYSTAL THERMOSET MONOMER OR OLIGOMER, THERMOSETTING LIQUID CRYSTAL POLYMER COMPOSITION COMPRISING THE SAME AND PRINTED CIRCUIT BOARD USING THE SAME
7.	12/332,931	12/11/2008	CROSSLINKABLE THERMOSET MONOMER, COMPOSITION FOR PRODUCING PRINTED CIRCUIT BOARD COMPRISING THE THERMOSET MONOMER AND PRINTED CIRCUIT BOARD USING THE COMPOSITION
8.	12/633,127	12/08/2009	COMPOSITION FOR PRODUCING A BOARD AND PRINTED CIRCUIT BOARD USING THE

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For valuable consideration, the receipt of which is hereby acknowledged, *SAMSUNG ELECTRONICS CO., LTD.*, a corporation of the *Republic of Korea*, having its principal place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 443-742, Republic of Korea, hereby assigns to (1) **Samsung Electro-Mechanics Co., Ltd.**, a corporation organized and existing under the laws of the Country of Republic of Korea, having a place of business at **314, Maetan-3dong, Yeongtong-gu, Suwon-si, Gyeonggi-do 443-803, Republic of Korea**, and (2) **Samsung Fine Chemicals Co., Ltd.**, a corporation organized and existing under the laws of the Country of Republic of Korea, having a place of business at **190 Yeochon-dong, Nam-gu, Ulsan 680-090**, Republic of Korea, all of the right, title and interest of *SAMSUNG ELECTRONICS CO., LTD.*, in and to the patents and patent applications listed on the attached Schedule of U.S. Patents and Patent Applications.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

*SAMSUNG ELECTRONICS CO., LTD.*,  
*Republic of Korea Corporation*

By: Joon Han KIM 

Title: Vice President

Date: 04. 18. 2014

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